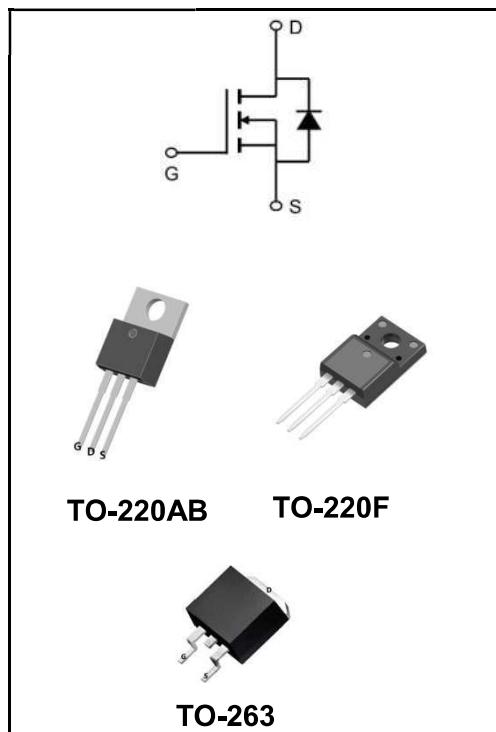


80V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	85A
V_{DSS}	80V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 8.5mΩ (Type: 6.5 mΩ)


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW85N08BT	TO-220AB	YFW 85N08BT XXXXX	1000PCS/box
YFW85N08BF	TO-220F	YFW 85N08BF XXXXX	1000PCS/box
YFW85N08BS	TO-263	YFW 85N08BS XXXXX	800PCS/Reel

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

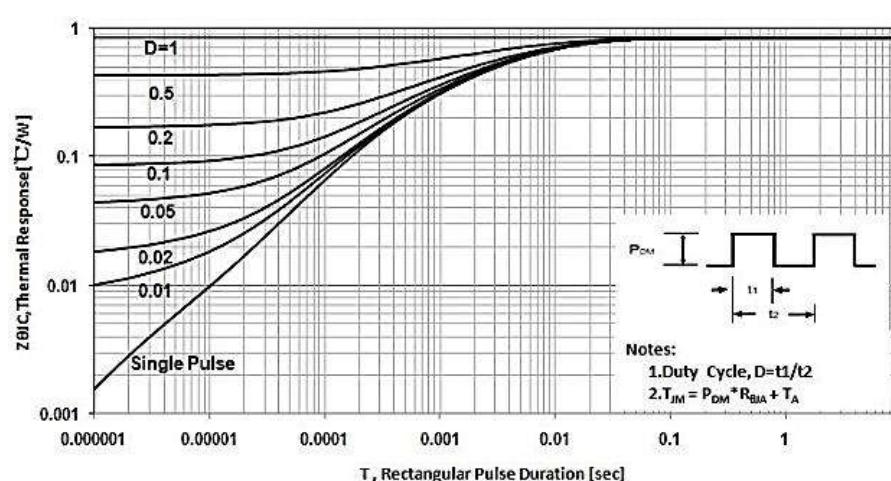
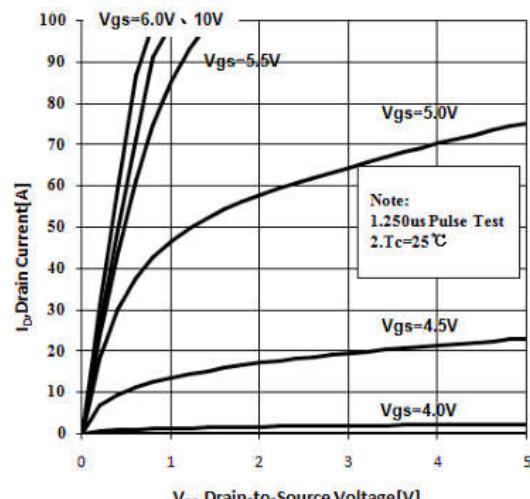
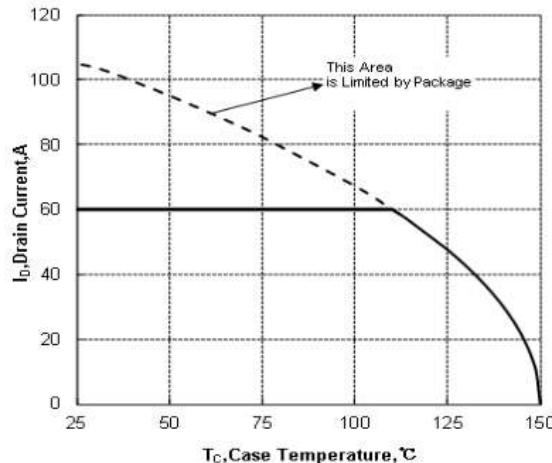
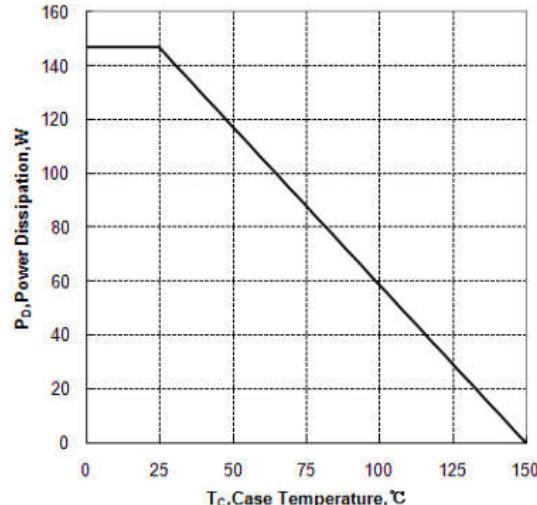
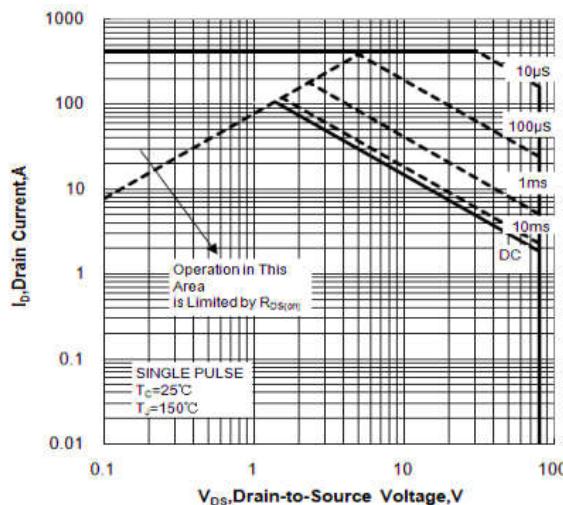
Characteristics	Symbols	Value	Units
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	80	V
Gate-Source Voltage ($V_{DS}=0V$)	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ 10V @ T_c=25^\circ\text{C}$	I_D	85	A
Continuous Drain Current, $V_{GS} @ 10V @ T_c=100^\circ\text{C}$	I_D	55	A
Drain Current-Continuous@ Current-Pulsed	I_{DM}	300	A
Maximum Power Dissipation($T_c=25^\circ\text{C}$)	P_D	160	W
Single pulsed avalanche energy	E_{AS}	550	mJ
Storage Temperature Range	T_{STG}	-55 to +150	A
Operating Junction Temperature Range	T_J	-55 to +175	°C
Thermal Resistance, Junction-Ambient	$R_{\theta JA}$	0.94	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	63	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	V(BR)DSS	80	85	-	V
Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA, T _j =25°C	V _{GS(th)}	2.0	3.0	4.0	V
Zero Gate Voltage Drain Current	V _{DS} =80V, V _{GS} =0V T _j =25°C	I _{DSS}	-	-	1	μA
	V _{DS} =80V, V _{GS} =0V T _j =125°C		-	-5	-	
Gate -Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Drain-source on-state resistance	V _{GS} =10V, I _D =50A, T _j =25°C	R _{DS(ON)}	-	6.5	8.5	mΩ
Transconductance	V _{DS} =5V, I _D =50V	g _f		80		S
Input Capacitance	V _{DS} =40V V _{GS} =0V f=1MHz	C _{iss}	-	2948	-	pF
Output Capacitance		C _{oss}	-	354	-	
Reverse Transfer Capacitance		C _{rss}	-	98	-	
Total Gate Charge	V _{DS} =40V I _D =50A V _{GS} =10V	Q _g	-	61	-	nC
Gate-Source Charge		Q _{gs}	-	13	-	
Gate-Drain Charge		Q _{gd}	-	24	-	
Turn-on delay time	T _j =25°C V _{GS} =10V V _{DS} =40V , R _L =3Ω,	t _{d(on)}	-	24	-	ns
Rise Time		T _r	-	15	-	
Turn-Off Delay Time		t _{d(OFF)}	-	52	-	
Fall Time		t _f	-	17	-	
Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	R _G	-	1.2	-	Ω
Body Diode Forward Voltage	V _{GS} =0V , I _{SD} =50A	V _{SD}	-	0.9	1.2	V
Body Diode Reverse Recovery Time	I _F =20A , dI/dt=500A/μs	t _{rr}	-	40	-	ns
		Q _{rr}	-	61	-	nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width .The EAS data shows Max. rating .
3. The test cond \leq 300us duty cycle \leq 2%, duty cycle condition is V_{DD}=64V V_{GS}=10V,L=0.1mH,I_{AS}=41A
4. The power dissipation is limited by 175°C junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves
Typical Characteristics


Ratings and Characteristic Curves

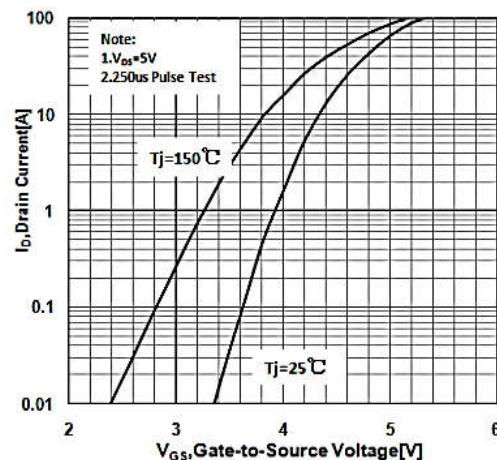


Figure 6 Typical Transfer Characteristics

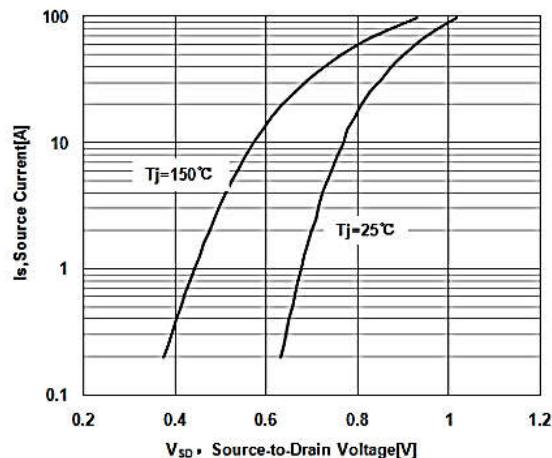


Figure 7 Typical Body Diode Transfer Characteristics

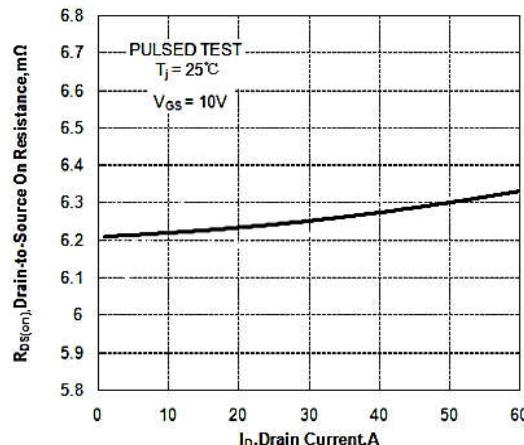


Figure 8. Drain-to-Source On Resistance vs Drain Current

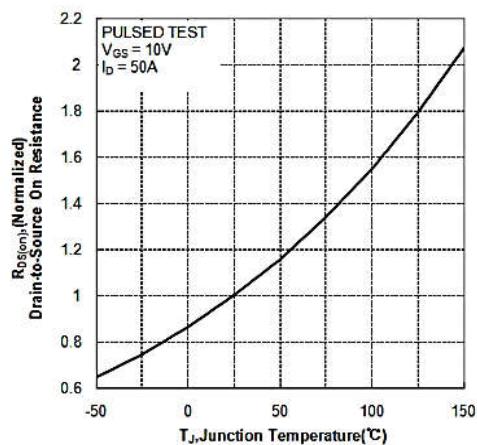


Figure 9. Normalized On Resistance vs Junction Temperature

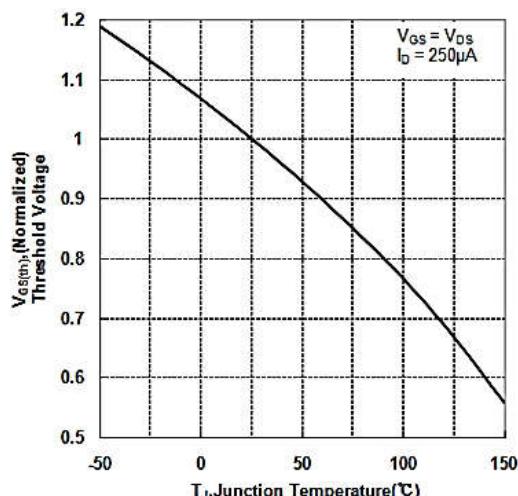


Figure10. Normalized Threshold Voltage vs Junction Temperature

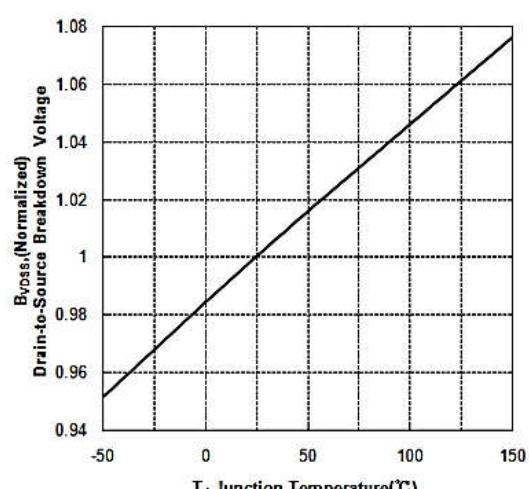


Figure 11. Normalized Breakdown Voltage vs Junction Temperature

Ratings and Characteristic Curves

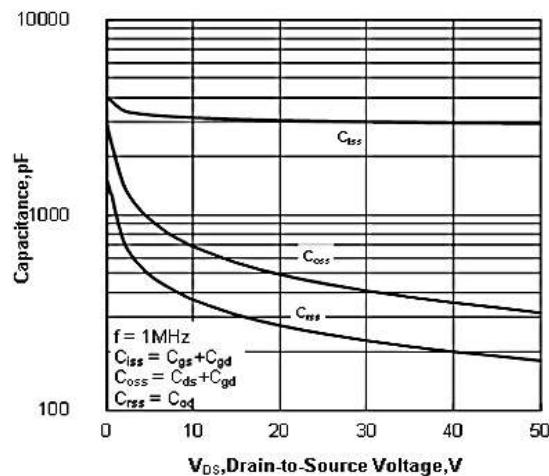


Figure 12. Capacitance Characteristics

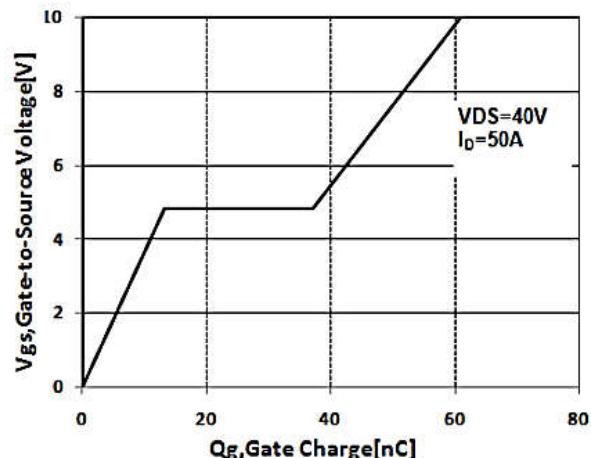
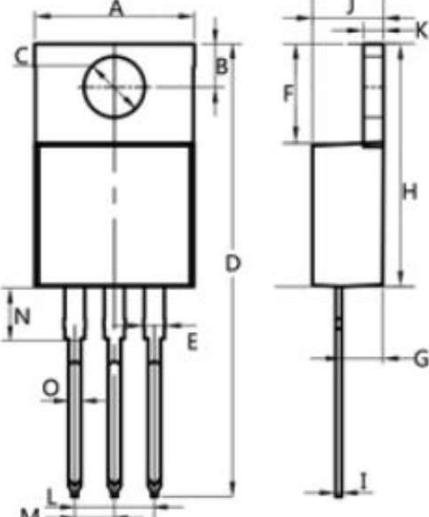


Figure 13 .Typical Gate Charge vs Gate to Source Voltage

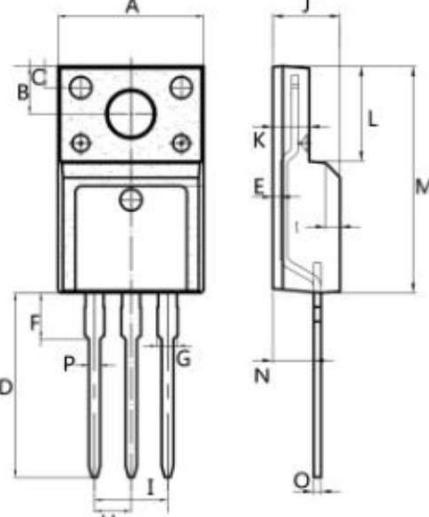
Package Outline Dimensions Millimeters

TO-220AB



Dim.	Min.	Max.
A	10.15	10.35
B	2.65	2.95
C	3.70	3.90
D	28.5	29.5
E	1.30	1.45
F	6.35	6.55
G	2.9	3.3
H	15.0	16.0
I	0.38	0.42
J	4.45	4.55
K	1.25	1.35
L	Typ 5.08	
M	Typ 2.54	
N	3.1	3.3
O	0.76	0.84
All Dimensions in millimeter		

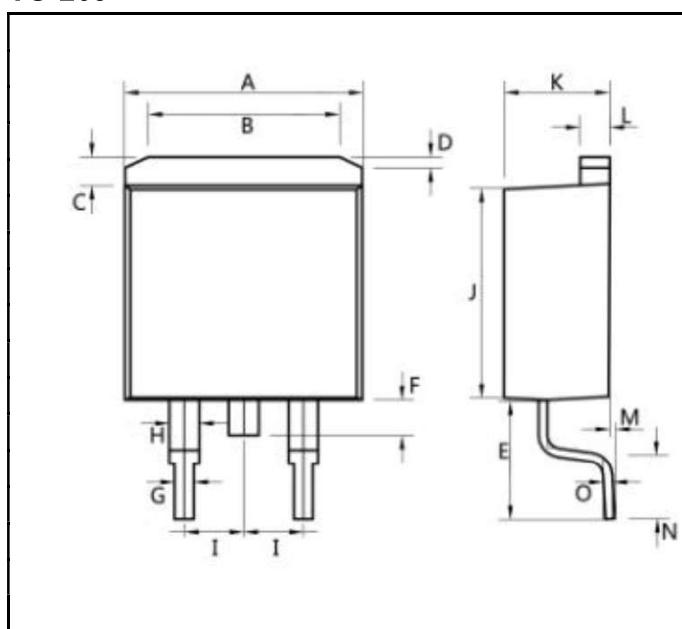
TO-220F



Dim.	Min.	Max.
A	9.95	10.25
B	2.95	3.25
C	1.25	1.45
D	12.95	13.25
E	0.50	0.65
F	3.1	3.3
G	1.30	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.60	4.75
K	2.50	2.65
L	6.35	6.55
M	15.4	16.0
N	2.75	3.05
O	0.48	0.52
P	0.76	0.84
All Dimensions in millimeter		

Package Outline Dimensions Millimeters

TO-263



The diagram illustrates the TO-263 package outline with two views: top-left and side-right. Key dimensions are labeled: A (width), B (width of body), C (height of body), D (lead thickness), E (lead height), F (lead pitch), G (lead thickness), H (lead height), I (lead pitch), J (total height), K (width of lead frame), L (lead thickness), M (lead thickness), N (lead pitch), and O (lead thickness). The side view shows the lead frame extending downwards from the body.

Dim.	Min.	Max.
A	10.1	10.2
B	7.4	7.6
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.78	0.86
H	1.2	1.3
I	Typ2.54	
J	8.4	8.6
K	4.45	4.55
L	1.25	1.35
M	0.02	0.1
N	2.4	2.8
O	0.36	0.40

All Dimensions in millimeter